

Electronic Patent Application Fee Transmittal

Application Number:	10593152			
Filing Date:	18-Sep-2006			
Title of Invention:	Electrodeposited Copper Foil with Carrier Foil on which a Resin Layer for Forming Insulating Layer is Formed, Copper-Clad Laminate, Printed Wiring Board, Method for Manufacturing Multilayer Copper-Clad Laminate, and Method for Manufacturing Printed Wiring Board			
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Filer:	Stephen M. Roylance/Annette Limberg			
Attorney Docket Number:	3209-124			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				810